



**THE DATASHEET OF  
SN74LVTH16652DGGR**

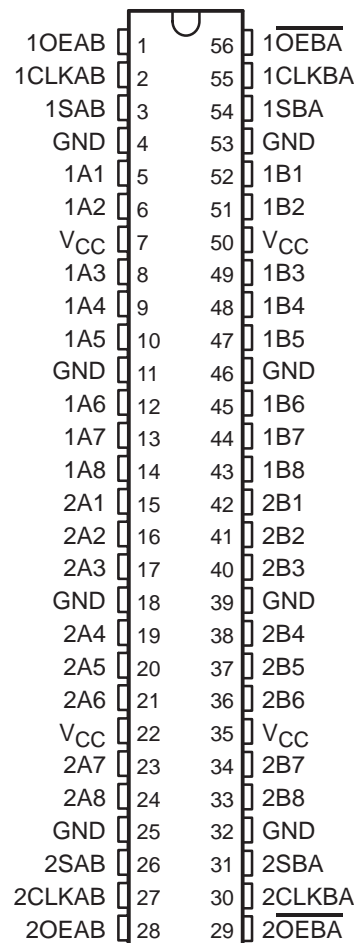


# SN54LVTH16652, SN74LVTH16652 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

- **Members of the Texas Instruments Widebus™ Family**
- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation**
- **Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )**
- **Support Unregulated Battery Operation Down to 2.7 V**
- **Typical  $V_{OLP}$  (Output Ground Bounce) < 0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$**
- **$I_{off}$  and Power-Up 3-State Support Hot Insertion**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Distributed  $V_{CC}$  and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ( $C = 200$  pF,  $R = 0$ )**
- **Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

**SN54LVTH16652 . . . WD PACKAGE  
SN74LVTH16652 . . . DGG OR DL PACKAGE  
(TOP VIEW)**



## description

The 'LVTH16652 devices are 16-bit bus transceivers designed for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable ( $\overline{OEAB}$  and  $\overline{OEBA}$ ) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVTH16652 devices.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1999, Texas Instruments Incorporated

# SN54LVTH16652, SN74LVTH16652

## 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS

### WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

#### description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

When  $V_{CC}$  is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, OE should be tied to  $V_{CC}$  through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16652 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74LVTH16652 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

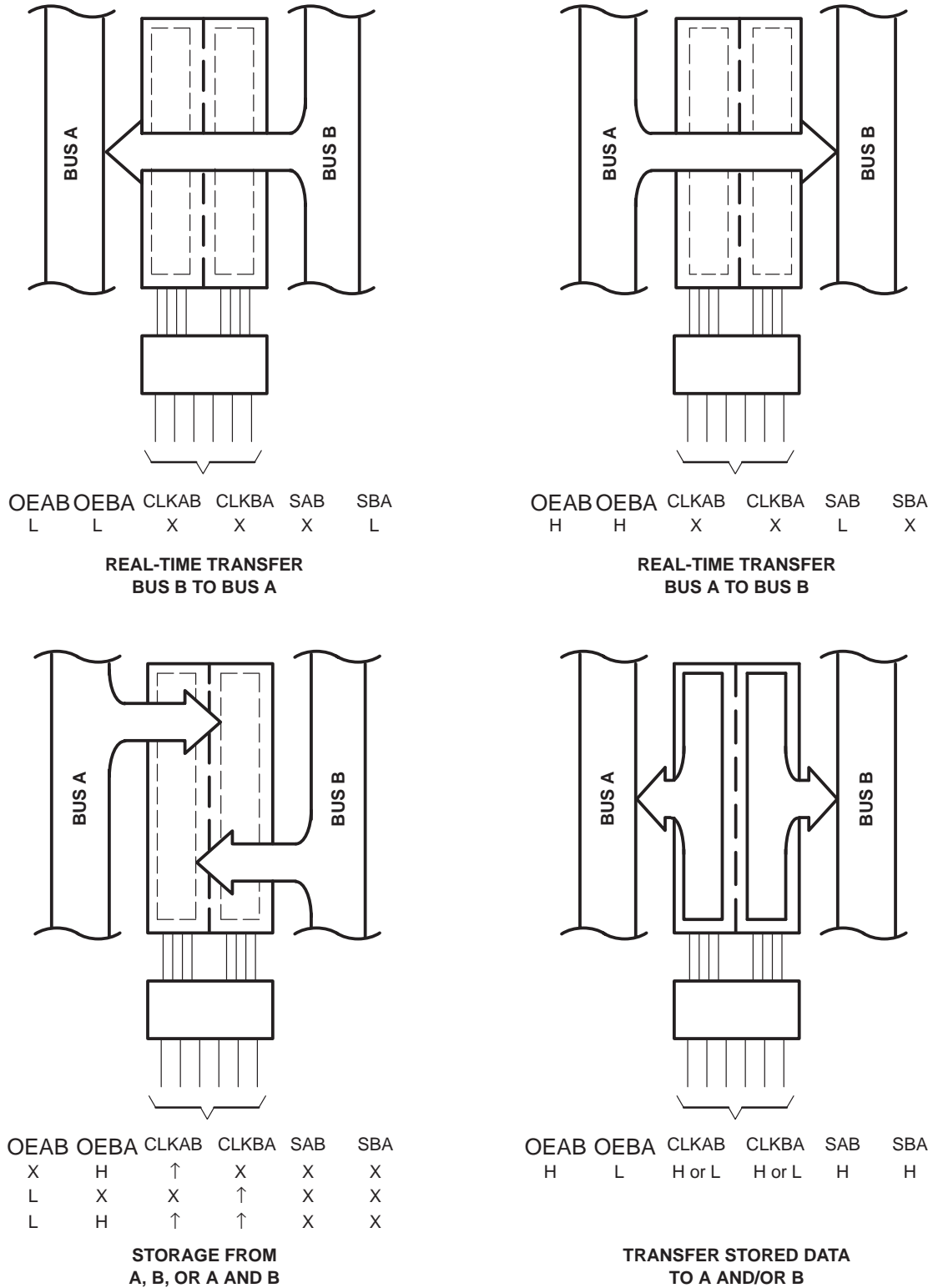
† The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

‡ Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.

SN54LVTH16652, SN74LVTH16652  
3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS  
WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999



BUS A	BUS B
-------	-------

OEAB	OEBA	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

**STORAGE FROM  
A, B, OR A AND B**

BUS A	BUS B
-------	-------

OEAB	OEBA	CLKAB	CLKBA	SAB	SBA
H	L	H or L	H or L	H	H

**TRANSFER STORED DATA  
TO A AND/OR B**

**Figure 1. Bus-Management Functions**

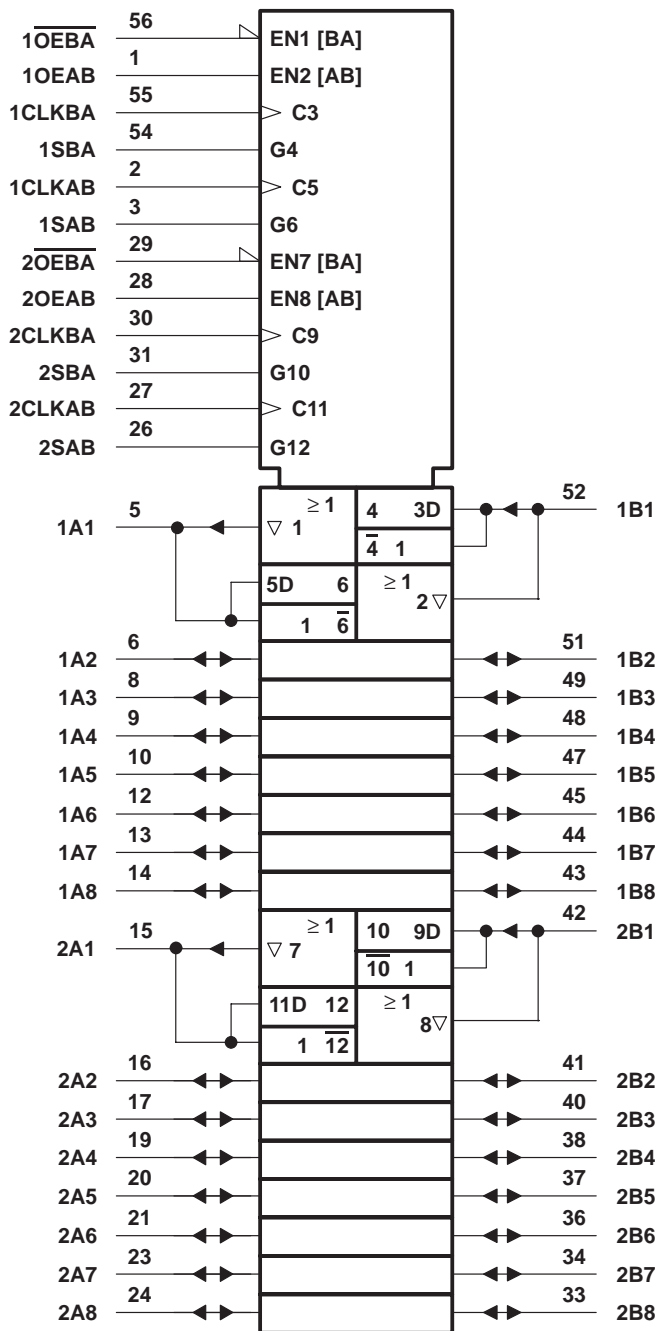
# SN54LVTH16652, SN74LVTH16652

## 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS

### WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

#### logic symbol†

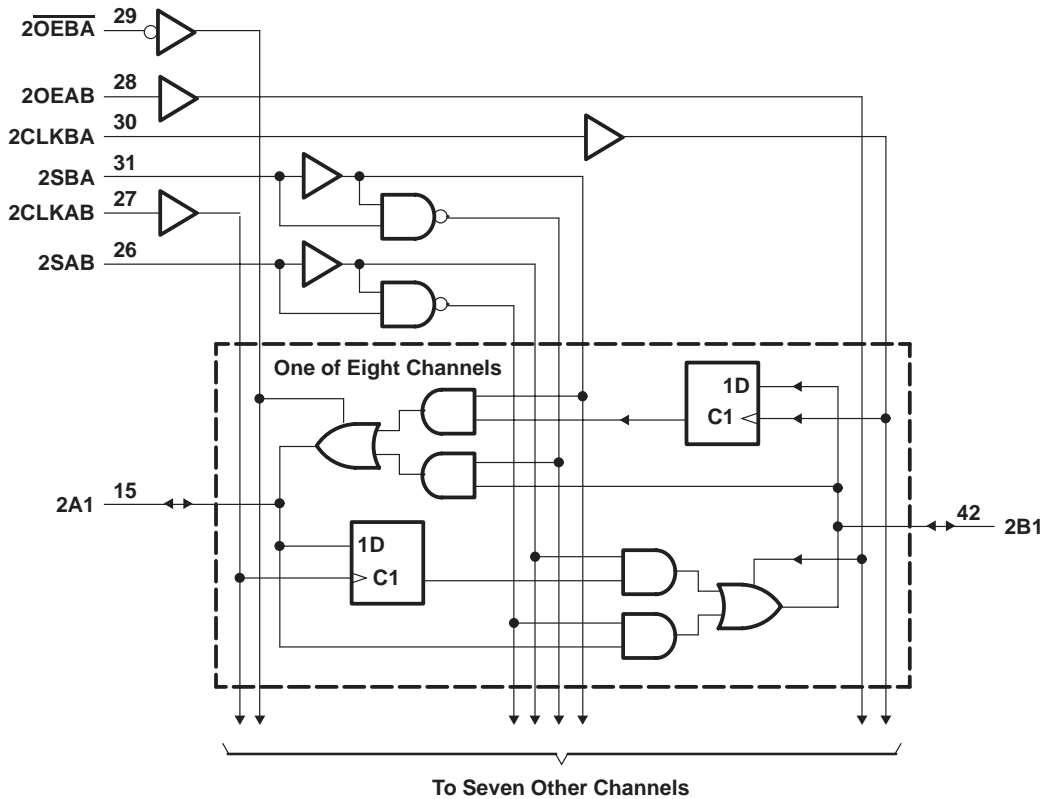
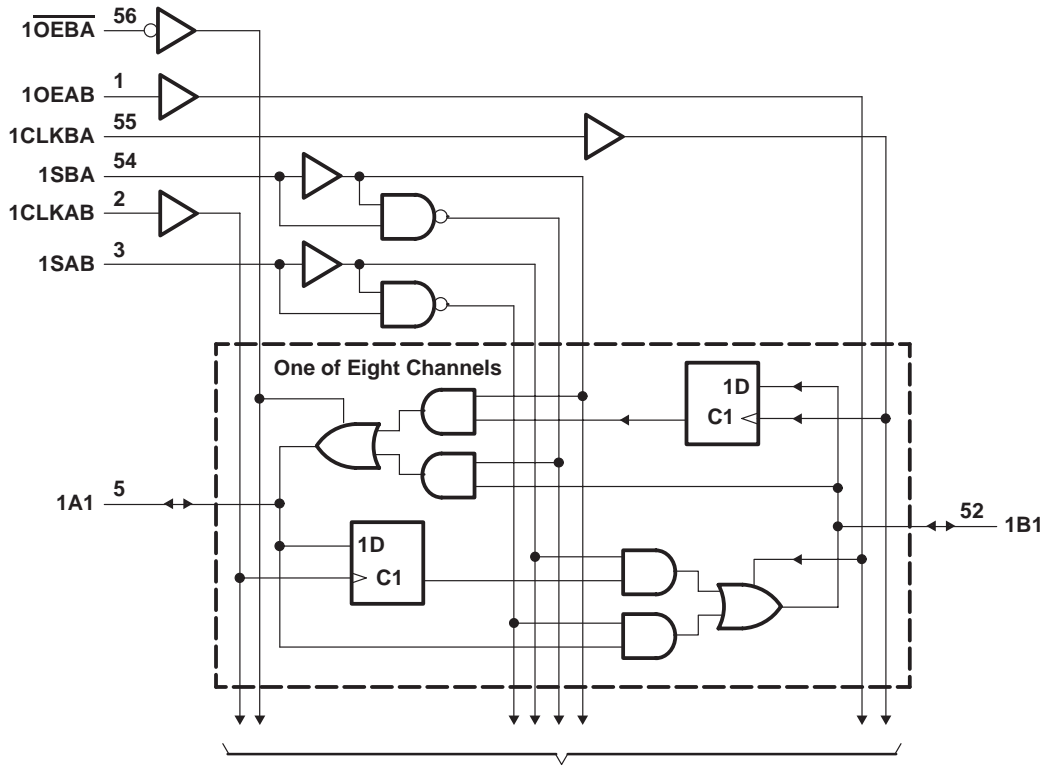


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54LVTH16652, SN74LVTH16652  
**3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS  
 WITH 3-STATE OUTPUTS**

SCBS150K – JULY 1994 – REVISED APRIL 1999

logic diagram (positive logic)



# SN54LVTH16652, SN74LVTH16652

## 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1) .....	-0.5 V to 7 V
Voltage range applied to any output in the high state, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, $I_O$ : SN54LVTH16652 .....	96 mA
SN74LVTH16652 .....	128 mA
Current into any output in the high state, $I_O$ (see Note 2): SN54LVTH16652 .....	48 mA
SN74LVTH16652 .....	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DGG package .....	81°C/W
DL package .....	74°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .  
 3. The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions (see Note 4)

		SN54LVTH16652		SN74LVTH16652		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	2.7	3.6	2.7	3.6	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage		5.5		5.5	V
$I_{OH}$	High-level output current		-24		-32	mA
$I_{OL}$	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		$\mu$ s/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54LVTH16652, SN74LVTH16652 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		SN54LVTH16652			SN74LVTH16652			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$		$V_{CC} = 2.7\text{ V}$ , $I_I = -18\text{ mA}$		-1.2			-1.2			V
$V_{OH}$		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$ , $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC}-0.2$			$V_{CC}-0.2$			V
		$V_{CC} = 2.7\text{ V}$ , $I_{OH} = -8\text{ mA}$		2.4			2.4			
		$V_{CC} = 3\text{ V}$		2			2			
		$I_{OH} = -24\text{ mA}$								
				$I_{OH} = -32\text{ mA}$						
$V_{OL}$		$V_{CC} = 2.7\text{ V}$		$I_{OL} = 100\text{ }\mu\text{A}$		0.2			0.2	V
				$I_{OL} = 24\text{ mA}$		0.5			0.5	
		$V_{CC} = 3\text{ V}$		$I_{OL} = 16\text{ mA}$		0.4			0.4	
				$I_{OL} = 32\text{ mA}$		0.5			0.5	
				$I_{OL} = 48\text{ mA}$		0.55				
				$I_{OL} = 64\text{ mA}$					0.55	
$I_I$		Control inputs $V_{CC} = 0\text{ or }3.6\text{ V}$ , $V_I = 5.5\text{ V}$ $V_{CC} = 3.6\text{ V}$ , $V_I = V_{CC}\text{ or GND}$		10			10			$\mu\text{A}$
				$\pm 1$			$\pm 1$			
$I_I$		A or B ports‡ $V_{CC} = 3.6\text{ V}$		$V_I = 5.5\text{ V}$		20			20	
				$V_I = V_{CC}$		1			1	
				$V_I = 0$		-5			-5	
$I_{off}$		$V_{CC} = 0$ , $V_I\text{ or }V_O = 0\text{ to }4.5\text{ V}$					$\pm 100$			$\mu\text{A}$
$I_I(\text{hold})$		A or B ports $V_{CC} = 3\text{ V}$		$V_I = 0.8\text{ V}$		75			75	$\mu\text{A}$
				$V_I = 2\text{ V}$		-75			-75	
		$V_{CC} = 3.6\text{ V}\S$ , $V_I = 0\text{ to }3.6\text{ V}$					$\pm 500$			
$I_{OZPU}$		$V_{CC} = 0\text{ to }1.5\text{ V}$ , $V_O = 0.5\text{ V to }3\text{ V}$ , OE/OE = don't care		$\pm 100^*$			$\pm 100$			$\mu\text{A}$
$I_{OZPD}$		$V_{CC} = 1.5\text{ V to }0$ , $V_O = 0.5\text{ V to }3\text{ V}$ , OE/OE = don't care		$\pm 100^*$			$\pm 100$			$\mu\text{A}$
$I_{CC}$		$V_{CC} = 3.6\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}\text{ or GND}$		Outputs high		0.19			0.19	mA
				Outputs low		5			5	
				Outputs disabled		0.19			0.19	
$\Delta I_{CC}\parallel$		$V_{CC} = 3\text{ V to }3.6\text{ V}$ , One input at $V_{CC} - 0.6\text{ V}$ , Other inputs at $V_{CC}\text{ or GND}$		0.2			0.2			mA
$C_i$		$V_I = 3\text{ V or }0$		4			4			pF
$C_{io}$		$V_O = 3\text{ V or }0$		10			10			pF

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Unused pins at  $V_{CC}\text{ or GND}$

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}\text{ or GND}$ .

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN54LVTH16652, SN74LVTH16652

## 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS

### WITH 3-STATE OUTPUTS

SCBS150K – JULY 1994 – REVISED APRIL 1999

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		SN54LVTH16652				SN74LVTH16652				UNIT
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency	150		150		150		150		MHz
$t_w$	Pulse duration, CLK high or low	3.3		3.3		3.3		3.3		ns
$t_{\text{su}}$	Setup time, A or B before CLKAB $\uparrow$ or CLKBA $\uparrow$	Data high	1.2	1.5	1.2	1.5			ns	
		Data low	2	2.8	2	2.8				
$t_{\text{h}}$	Hold time, A or B after CLKAB $\uparrow$ or CLKBA $\uparrow$	Data high	0.5	0	0.5	0			ns	
		Data low	0.5	0.5	0.5	0.5				

switching characteristics over recommended operating free-air temperature range,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 2)

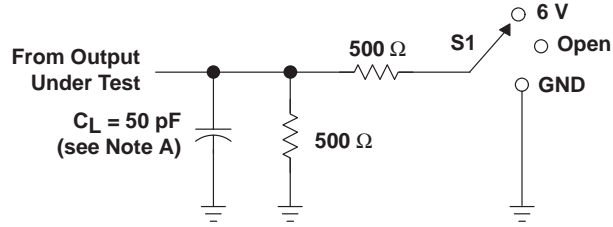
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16652				SN74LVTH16652				UNIT	
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP $\dagger$	MAX	MIN		MAX
$f_{\text{max}}$			150		150		150			150		MHz
$t_{\text{PLH}}$	CLK	B or A	1.3	4.5	5		1.3	2.7	4.2	4.7		ns
$t_{\text{PHL}}$			1.3	4.5	5		1.3	2.8	4.2	4.7		
$t_{\text{PLH}}$	A or B	B or A	1	3.6	4.1		1	2.4	3.4	3.9		ns
$t_{\text{PHL}}$			1	3.6	4.1		1	2.1	3.4	3.9		
$t_{\text{PLH}}$	SAB or SBA	B or A	1	4.7	5.6		1	2.7	4.5	5.4		ns
$t_{\text{PHL}}$			1	4.7	5.6		1	3	4.5	5.4		
$t_{\text{PZH}}$	$\overline{\text{OEBA}}$	A	1	4.5	5.4		1	2.4	4.3	5.2		ns
$t_{\text{PZL}}$			1	4.5	5.4		1	2.3	4.3	5.2		
$t_{\text{PHZ}}$	$\overline{\text{OEBA}}$	A	2	5.8	6.3		2	3.9	5.6	6.1		ns
$t_{\text{PLZ}}$			2	5.6	6.3		2	3.4	5.4	6.1		
$t_{\text{PZH}}$	OEAB	B	1.3	4.4	5.1		1.3	2.7	4.2	4.9		ns
$t_{\text{PZL}}$			1.3	4.4	5.1		1.3	2.6	4.2	4.9		
$t_{\text{PHZ}}$	OEAB	B	1.6	5.8	6.5		1.3	3.5	5.5	6.2		ns
$t_{\text{PLZ}}$			1.6	5.8	6.5		1.3	3.2	5.5	6.2		

$\dagger$  All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

SN54LVTH16652, SN74LVTH16652  
3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS  
WITH 3-STATE OUTPUTS

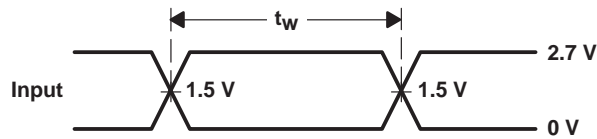
SCBS150K – JULY 1994 – REVISED APRIL 1999

**PARAMETER MEASUREMENT INFORMATION**

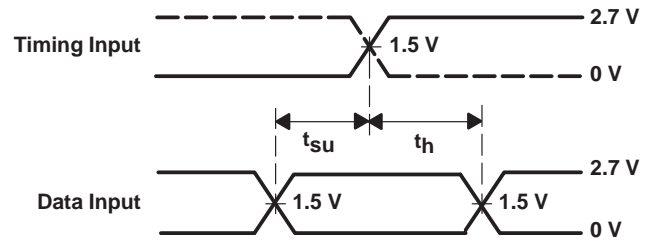


**LOAD CIRCUIT**

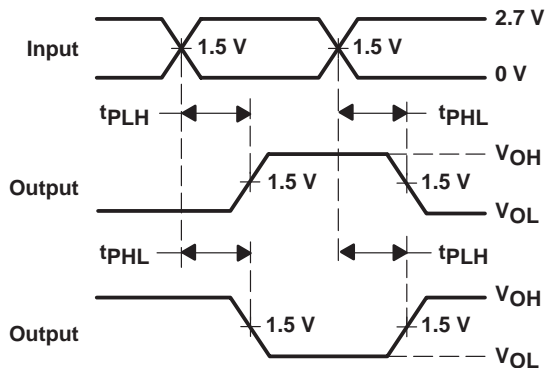
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



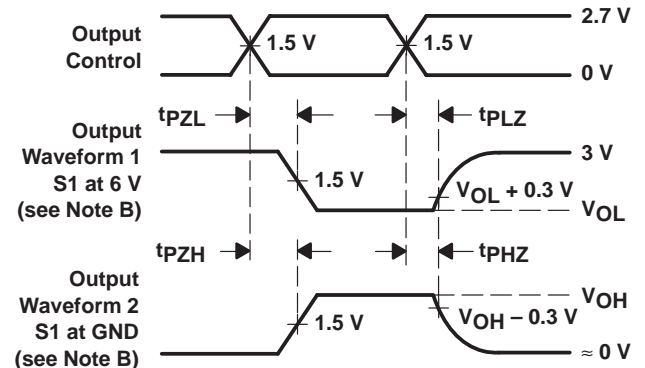
**VOLTAGE WAVEFORMS  
PULSE DURATION**



**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.

**Figure 2. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVTH16652DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16652	<a href="#">Samples</a>
SN74LVTH16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16652	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LVTH16652 :**

- Enhanced Product: [SN74LVTH16652-EP](#)

**NOTE: Qualified Version Definitions:**

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16652DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16652DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0





# EXAMPLE BOARD LAYOUT

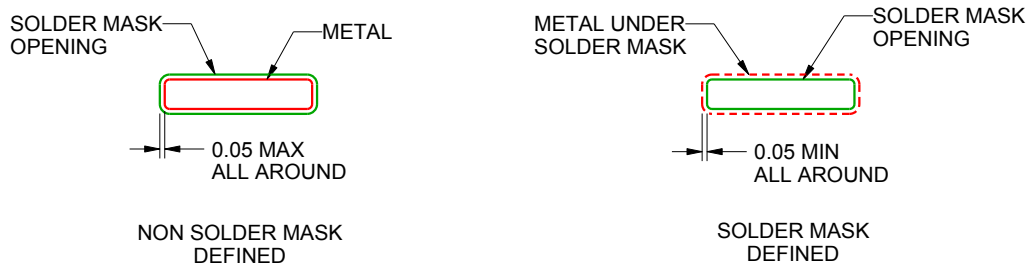
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)





## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View SN74LVTH16652DGGR on WIN SOURCE](#)

 [Texas Instruments](#) Information

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management